

## PMT Orders Maskless Lithography System from EVG for Wafer Probe Card Manufacturing— January 26, 2024

# semiconductor packaging news

News Focused on Semiconductor Packaging

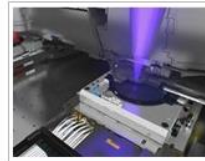
HOME PAPERS SUBSCRIBE TRANSLATE

January 26, 2024

### [China Imports Over 400 Lithography Machines from Netherlands Past Five Years](#)

China's ASML rival, AMEC, makes strides in semiconductor manufacturing with its lithography equipment. Partnering with the Netherlands' ASML may challenge ASML's global dominance in the industry.

Digitimes



#### [Silver Filled Epoxy for Die Attach](#)

Master Bond EP3HTS-TC is a one part, NASA low outgassing rated epoxy, with excellent thermal conductivity that features a thixotropic paste consistency.

Master Bond



#### [No-Clean, Flip-Chip & Ball-Attach Flux](#)

Improve yields with NC-809, the industry leading, true no-clean, ultra-low residue, flip-chip and ball-attach flux suitable for many semiconductor applications.

Indium Corporation



### [VIEWPOINT 2024: Andy Behr, Technology Manager, Panasonic Electronic Materials](#)

2023 was a busy year for the IC Packaging Industry writ large and for Panasonic Electronic Materials as well. Ignited by AI adoption, the Networking/Data Center sector drove significant growth and activity for both our printed circuit board and IC Packaging business units. Geographically, we're not yet experiencing ...

Panasonic Electronic Materials



#### [Series B: Adhesion and Bondability of Al2O3-coated Bonding Wire](#)

Using Atomic Layer Deposition (ALD), we applied a nanoscale Al2O3 ceramic coating to metal bonding wires, enhancing adhesion, insulation, and corrosion resistance ...

Technical Paper

### [TSMC Reports 4Q2023 Earnings: N2 Still On Track For 2025 Production](#)

TSMC's Q4 2023 earnings report reveals continued progress towards its N2 semiconductor fabrication technology, remaining on schedule for production in 2025. Strong financial performance underscores the company's commitment to advancing cutting-edge chip manufacturing.

Semiconductor Engineering

#### Technical Papers

- [Highly Selective Epoxy Molding Compound Removal in Advanced Semiconductor Devices](#)
- [Motivation for pressure-assisted metallic sintering in Power Electronics](#)
- [IR Laser Cleave Technology for 3D Packaging and Logic Scaling](#)
- [Next Gen Laser Assisted Bonding \(LAB\) Technology](#)
- [Durability and Cost Benefits Drive Mil-Aero Demand for OCPP](#)
- [Revising 5G RF Calibration Procedures For RF IC Production Testing](#)
- [Optimizing New Power Switch Technology Using Compound Semiconductors](#)

#### [Plasma Treatment during FOWLP Optimizes Performance and Costs](#)

Fan-out Wafer-Level (FOWLP) & Fan-out Panel-Level (FOPLP) benefit from plasma treatment, which ensures surfaces are contamination-free. Read more



MARCH | Nordson Electronics Solutions

Today's Sponsor



#### Test Your Knowledge

List these inventions in chronological order: Television, Polaroid Camera, Tape Recorder  
See answer below.



#### Press Releases

##### [Chiplets are rising: where and when?](#)

Yole Group is part of Chiplet Summit 2024. The Summit occurs on February 6-8 at the Santa Clara Convention Center. The Chiplet Summit program is now available here. ...

Yole Group

##### [PMT Orders Maskless Lithography System from EVG for Wafer Probe Card Manufacturing](#)

PROTEC MEMS Technology (PMT) has ordered a LITHOSCALE® maskless exposure system from EV Group (EVG), a leading supplier of wafer bonding and lithography equipment ...

EV Group

##### [SPIE Photonics West 2024 to Feature Kyocera's Optical Components](#)

Kyocera will exhibit its latest optoelectronic products and technologies at two upcoming events in San Francisco's Moscone Center: SPIE Photonics West 2024 (Jan. 30 to Feb. 1) ...

Kyocera International, Inc.

### Alternatives to Isopropyl Alcohol (IPA)

Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!



**KYZEN**

### Contaminant Removal with Plasma

Plasma provides organics removal and other benefits to increase bond strength! Many chamber sizes available, all with a low environmental impact. Learn more.



**Plasma Etch**

### Invitation to presentation of Mycronic's Q4 2023

Analysts, investors and media are invited to the presentation of Mycronic's Q4 2023. The presentation will be held on February 8, 2024, at 10:00 a.m. CET. The report ...

**Mycronic AB**

### Pristine Surfaces with Atmospheric Plasma

Plasma cleaning options, from lab/demo units all the way to custom engineered, integrated, full-scale. [Click Here](#) to learn more.



**Ontos Equipment Systems**

### Quote of the Day

"The Internet is like a giant jellyfish. You can't step on it. You can't go around it. You've got to get through it."

**John Evans**

### e-media Advertising Delivers Results!

Introduce your products & technology in Semiconductor Packaging News with our daily e-mail newsletter & website and see how a digital advertising campaign can deliver results.



**Semiconductor Packaging News**

### The Gold Standard of Bond Testing

Royce Instruments has been designing and building bond test equipment for over 30 years. The line of bond test equipment offers unmatched precision & robust operation for all your needs.



**Royce Instruments**

### The day was Jan 26. What year was it?

**Australia Day**

Captain Arthur Phillip guides a fleet of 11 British ships carrying convicts to the colony of New South Wales, effectively founding Australia.



See the answer below.

### Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages

New fault isolation technique using 3D X-ray microscopy & LaserFIB to pinpoint, isolate & open a 20 µm wirebond without damage to adjacent wires.



**ZEISS Microscopy**

### EDA Back On Investors' Radar

Investors are once again showing keen interest in the Electronic Design Automation (EDA) sector. With the semiconductor industry's growing importance, EDA companies are poised for potential growth, making them attractive investment opportunities.

**Semiconductor Engineering**

### SEMI Applauds Announcement of European Economic Security Strategy

Semiconductors are driving the AI revolution, enabling faster and more efficient artificial intelligence applications. This technological synergy promises to reshape industries and enhance AI capabilities across the board.

**SEMI**

### Apple's iPhone China shipments down 2.1% in the final quarter of last year

Apple faced a 2.1% decline in smartphone shipments in China during 3Q23, as local competitors, notably Huawei, intensified their presence. This setback reflects the mounting challenges Apple confronts, partly due to Chinese firms and govt agencies restricting the use of Apple devices, echoing US restrictions on Chinese apps.

**Taipei Times**



### German semiconductor students to arrive in March

Thirty students from Saxony, Germany, are set to arrive in Taiwan in March for semiconductor manufacturing training, part of a talent incubation program by TSMC, Saxony government, and TU Dresden. This partnership aims to support TSMC's new fab in Dresden.

**Taipei Times**

### Apple takes top spot in China's smartphone market for the first time as Huawei returns to the top 5

In a historic milestone, Apple has seized the top position in China's smartphone market for the very first time, beating out its competitors and solidifying its dominance in this crucial global tech hub.

**CNBC**

### Respect? Confused

In a puzzling turn of events, the semiconductor industry faces growing uncertainty and a lack of respect from policymakers, potentially jeopardizing its crucial role in technological advancements and economic stability.

**Semiconductor Engineering**

### Die Bonding Made Easy

The DL Technology X-Form needles are custom manufactured for conductive epoxy dispensing in die bonding applications. Each needle is machined using DL's patented EZ-FLO.



**DL Technology**

### Particle-Free Plasma Oxide Reduction

Ar/H2 plasma for flux-free flip chip bonding. Low temp, uniform 100 mm wide beams. Fast oxide removal. No damage or particles. Contact us for integration into your TCB bonder.



**Surfx Technologies**





### [SK hynix swings to Q4 operating profit on rising demand for premium chips](#)

SK hynix Inc. announced a fourth-quarter profit of 346 billion won (\$259.4 million), a significant turnaround from the previous year's 1.91 trillion won loss, thanks to surging demand for premium memory chips. Despite a net loss of 1.37 trillion won, the company reported a 47.4% increase in sales to 11.3 trillion won.

Yonhap News Agency

House up to 6 sensors

Put it to the test!

xyztec

PacTech

3D Solder Jetting

SB<sup>+</sup>SMs Quantum

www.pactech.de

plasmatreat

Openair-Plasma<sup>®</sup> for flux free oxide reduction

Click here for more

### Cartoon of the Day



"The computer is tired of you taking all the credit and it's demanding half of your paycheck."

Copyright © Randy Glasbergen

Advertisement  
300 x 150

### Calendar

- [Jan 31, 2024: SEMICON Korea](#)
- [Feb 13, 2024: SMTA Wafer-Level Packaging Symposium](#)
- [Mar 20, 2024: SEMICON CHINA](#)
- [Jun 12, 2024: 3D & Systems Summit](#)

#### Die Bonding Made Easy

The DL Technology X-Form needles are custom manufactured for conductive epoxy dispensing in die bonding applications. Each needle is machined using DL's patented EZ-FLO.

**DL Technology**



#### Particle-Free Plasma Oxide Reduction

Ar/H<sub>2</sub> plasma for flux-free flip chip bonding. Low temp, uniform 100 mm wide beams. Fast oxide removal. No damage or particles. Contact us for integration into your TCB bonder.

**Surfx Technologies**



### Test Your Knowledge Answer

List these inventions in chronological order:

Television, Polaroid Camera, Tape Recorder

Answer: Tape Recorder-1899, Television-1926,

Polaroid Camera-1947

### What Year Was It Answer

Australia Day

Answer: January 26, 1788

[NEWSLETTER ARCHIVES](#)

[About Us](#) | [Advertising](#) | [Archives](#) | [Calendar](#) | [Contact Us](#) | [Custom Email Broadcast](#) | [Disclaimer](#) | [Exclusives](#) | [News](#) | [Press Releases](#) | [Press Release Submit](#) | [Privacy Policy](#) | [Search](#) | [Subscription](#) | [Viewpoint](#) | [White Papers](#) | [White Paper Submit](#)

#### Circuitnet Media, LLC

6 Liberty Square #2040, Boston MA 02109 USA

Jeff Ferry, Publisher | Ken Cavallaro, Editor/Business Manager

Copyright © Circuitnet Media LLC. All rights reserved.

[A Circuitnet Media Publication](#)

ISSN 2768-2706

This email was sent to [dmoreno@openskypr.com](mailto:dmoreno@openskypr.com) - [Unsubscribe](#)  
[Add us to your address book](#)